

#5/A
5-28-02
Mural

Our File No.: SPLX.P0068

CERTIFICATE OF MAILING BY "FIRST CLASS MAIL"

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on Wednesday, October 03, 2001.

Dag Johansen

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application for:

Steven Teig, et al.

Serial No.: <not assigned yet>

Filing Date: <not assigned yet>

For: METHOD AND ARRANGEMENT FOR
LAYOUT AND MANUFACTURE OF
GRIDLESS NON MANHATTAN
SEMICONDUCTOR INTEGRATED
CIRCUITS

Examiner: <not assigned yet>

Group Art Unit: <not assigned yet>

PRELIMINARY AMENDMENT

Assistant Commissioner of
Patents and Trademarks
Washington, D.C. 20231

Sir:

Please amend the above-identified patent application as follows before examining the claims. This Preliminary Amendments is concurrently filed with the above-entitled application, which is a continuation application of a presently pending application entitled "Method And Arrangement For Layout And Manufacture Of Gridless Non Manhattan Semiconductor Integrated Circuits," filed on 6/3/01. **Applicants**

09972011-10501